

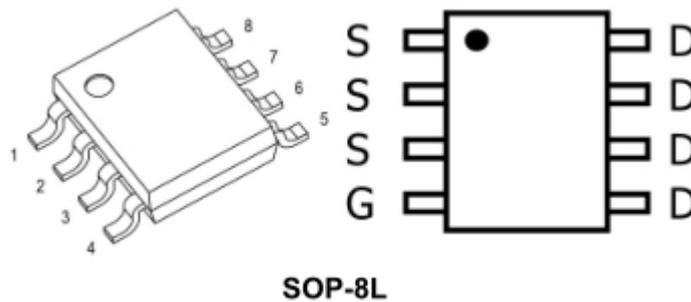
Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	3.8mΩ@10V	15A
	5.8mΩ@4.5V	

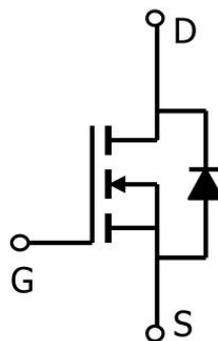
Feature

- $V_{DS} = 30V, I_D = 15A$
- $R_{DS(ON)} = 3.8m\Omega$ (typical) @ $V_{GS} = 10V$
- $R_{DS(ON)} = 5.8m\Omega$ (typical) @ $V_{GS} = 4.5V$
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

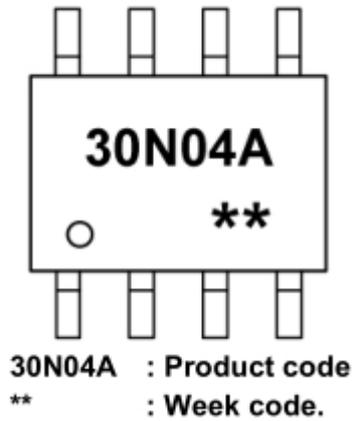
Package



Circuit diagram



Marking



Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	15	A
Pulsed Drain Current	I _{DM}	60	A
Maximum Power Dissipation	P _D	3	W
Thermal Resistance,Junction-to-Case	R _{θJC}	41.7	°C/W
Operating Junction and Storage Temperature Range	T _{STG, T_J}	-55 To 150	°C

Electrical characteristics

($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-source breakdown voltage	$BV_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 30V, V_{GS} = 0V$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	μA
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2.5	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 12A$		3.8	5.8	$m\Omega$
		$V_{GS} = 4.5V, I_D = 10A$		5.8	8.8	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = 15V, V_{GS} = 0V,$ $f = 1MHz$		3500		pF
Output Capacitance	C_{oss}			380		
Reverse Transfer Capacitance	C_{rss}			290		
Switching Characteristics						
Turn-On Delay Time	$T_{d(on)}$	$V_{DD} = 15V, I_D = 20A,$ $V_{GS} = 10V, R_{GEN} = 3\Omega$		12		nS
Rise Time	T_r			15		
Turn-Off Delay Time	$T_{d(off)}$			40		
Fall Time	T_f			14		
Total Gate Charge	Q_g	$V_{DS} = 15V, I_D = 45A,$ $V_{GS} = 10V$		60		pF
Gate-Source Charge	Q_{gs}			8.2		
Gate-Drain Charge	Q_{gd}			16.4		
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 1A$			1.2	V

Typical Characteristics

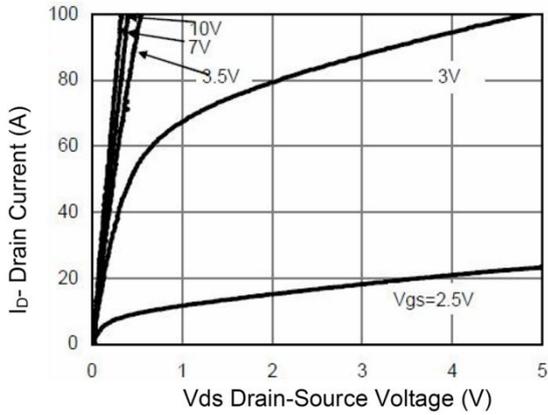


Figure 1 Output Characteristics

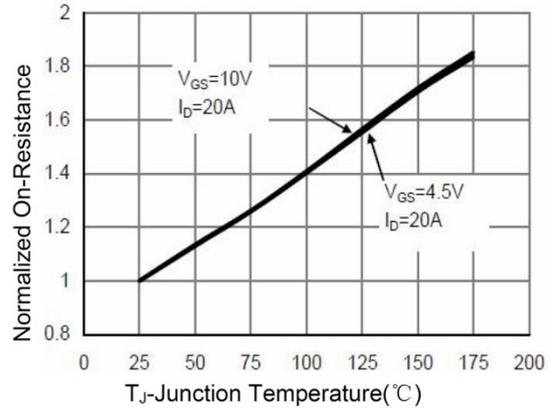


Figure 4 Rdson-Junction Temperature

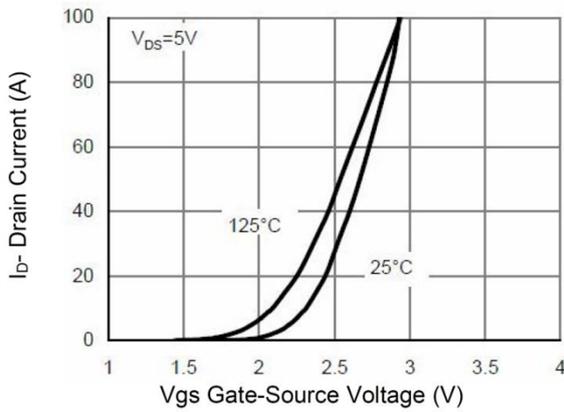


Figure 2 Transfer Characteristics

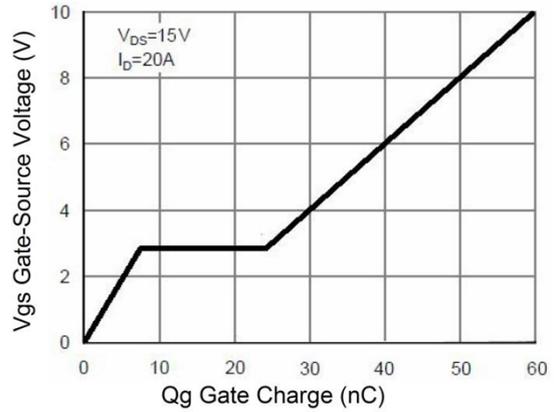


Figure 5 Gate Charge

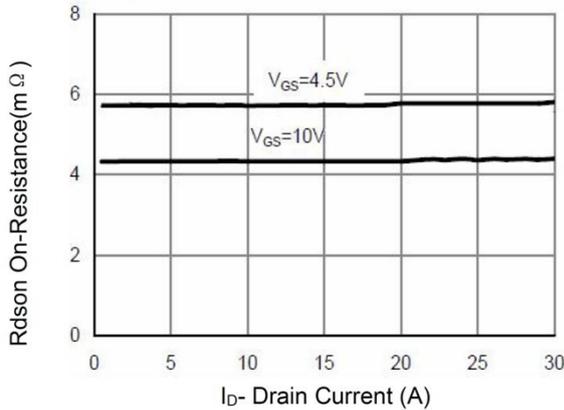


Figure 3 Rdson- Drain Current

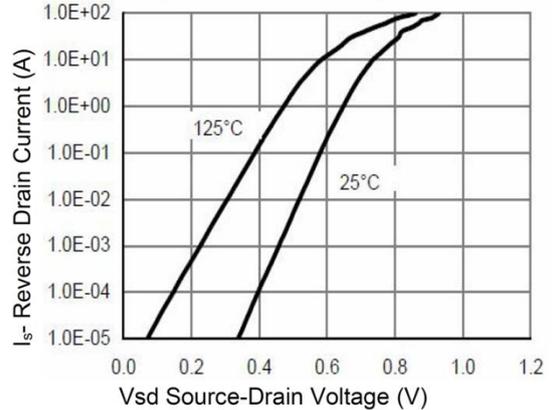


Figure 6 Source- Drain Diode Forward

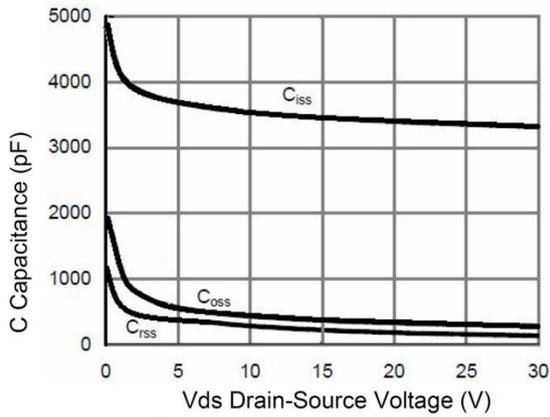


Figure 7 Capacitance vs Vds

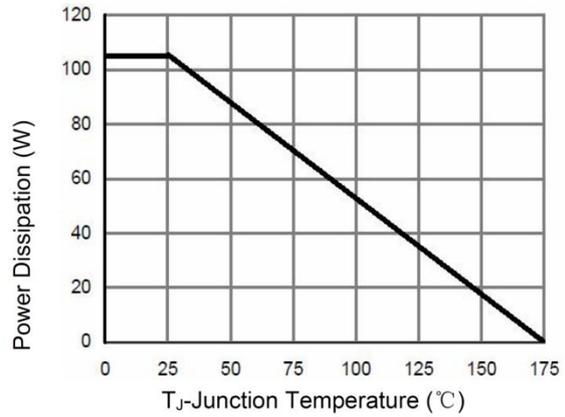


Figure 9 Power De-rating

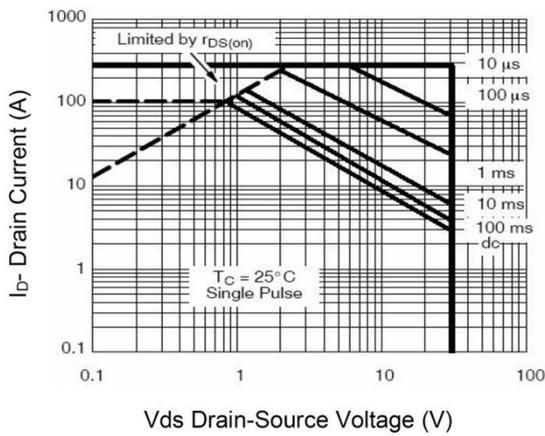


Figure 8 Safe Operation Area

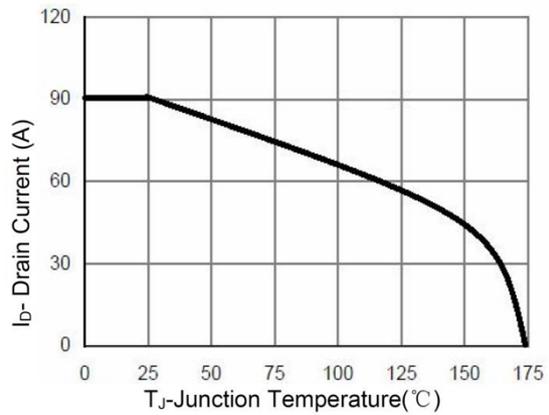


Figure 10 ID Current Derating

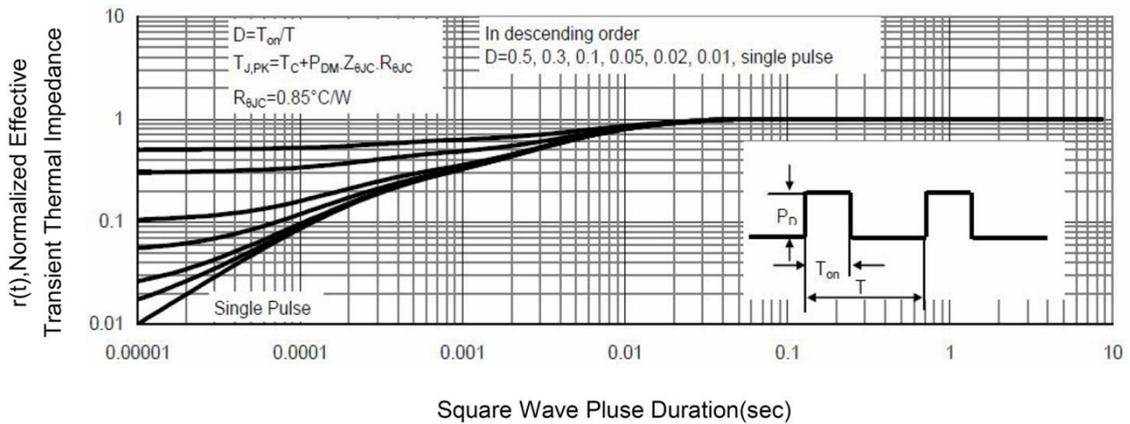
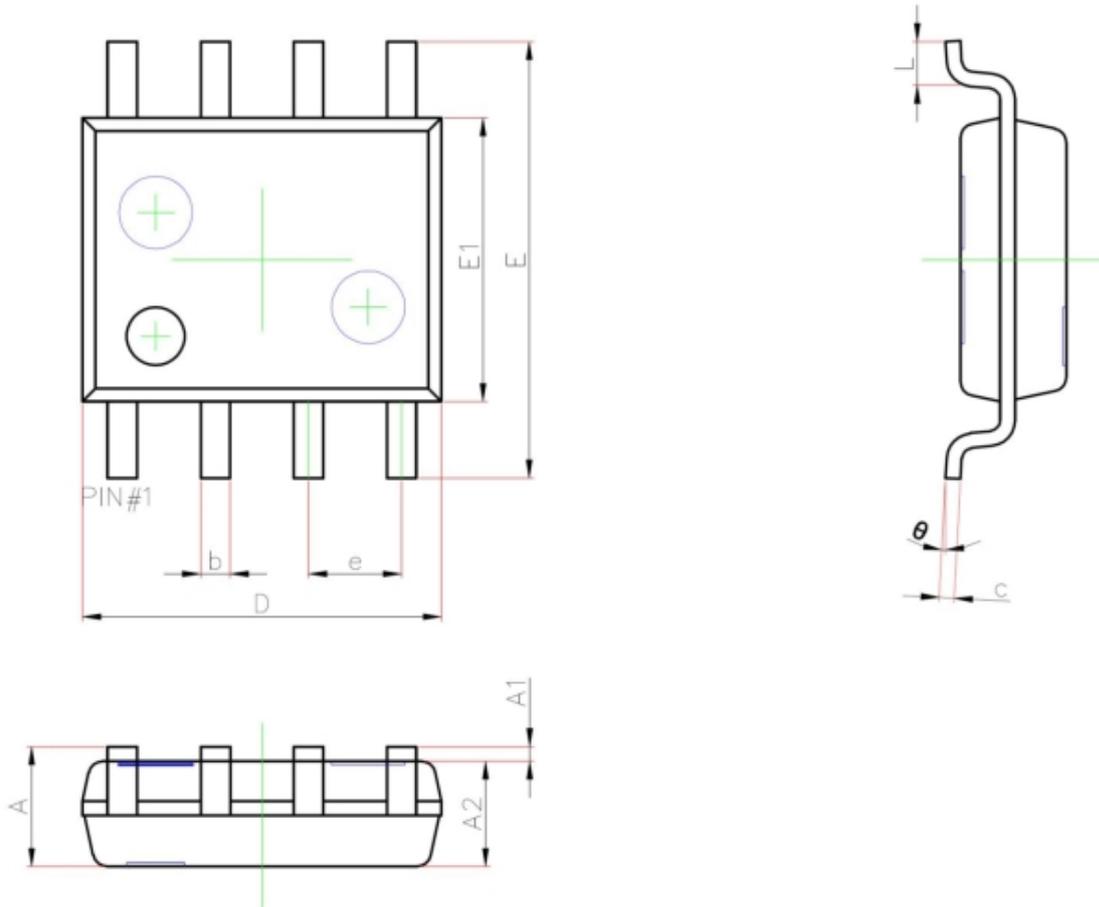


Figure 11 Normalized Maximum Transient Thermal Impedance

SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°